

GENERAL TECHNICAL SPECIFICATIONS FOR

6994-iss2 Card

GENERAL SPECIFICATION

- 1) All the trace width specified in the gerber are finished trace widths and are maximum.
- 2) 12-Layer PCB with both through hole and SMD components.

PCB SPECIFICATION

- | | | |
|-------------------------------------|---|----------------------|
| 1) PCB name | : | 6994-iss2 |
| 2) PCB-type | : | 12 layer |
| 3) Density Classification | : | IPC-6012 Class2 |
| 4) ML Build-up | : | Customer Build-up |
| 5) No. of reference layers | : | 10 |
| 6) Required Impedance Tolerance | : | Yes |
| 7) Material | : | FR4,170 Deg Tg |
| 8) Length | : | 206 mm |
| 9) Width | : | 160 mm |
| 10) Thickness | : | 1.60 mm |
| 11) Surface Plating | : | ENIG |
| 12) Photo Imageable Solder Mask | : | 2 Nos. |
| 13) Component legend (in white ink) | : | 2 No. |
| 14) Stack-up | : | As per attached file |

TRACE DETAILS

- | | | |
|---------------------------|---|-----------------------------------|
| 1) Min. trace Width | : | 3.5 mils in all electrical layers |
| 2) Min Trace to Trace Gap | : | 4 mils in all electrical layers |
| 3) Min Drill | : | 8 mil |

IMPEDANCE TABLE:

Layer#	500HM (Mils)	900HM (Mils)		1000HM (Mils)		REFERENCE LAYER
		TW	SPACING	TW	SPACING	
L01_TOP	7.3	6	6	4.8	6.6	L02-GND
L03-SIG1	4	4.5	7.0	3.7	8	L02-GND
L05-SIG2	3.8	4.5	7.5	3.5	7	L04-GND
L08-SIG3	3.8			3.5	7	L07-GND
L10-SIG4	4	4.5	7	3.7	8	L09-GND
L12-BOT	7.3	6	6	4.8	6.6	L11-GND